

SMD ■ TOP View LEDs EAPL3527RA0-AM

PRELIMINARY



Features

- P-LCC-2 package.
- White package.
- Optical indicator.
- Colorless clear window.
- Wide viewing angle.
- Suitable for vapor-phase reflow, Infrared reflow and wave solder processes.
- Computable with automatic placement equipment.
- Available on tape and reel (8mm Tape).
- Pb-free
- The product itself will remain within RoHS compliant version.

Description

This series is available in soft orange, green, blue and yellow. Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes ideal for light pipe application. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.

Applications

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- Light pipe application.
- General use.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Dark Red	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	60	mA
Power Dissipation	P_d	60	mW
Junction Temperature	T_j	115	°C
Operating Temperature	T_{opr}	-40 ~ +100	°C
Storage Temperature	T_{stg}	-40 ~ +110	°C
Thermal Resistance	$R_{th\ J-A}$	500	K/W
	$R_{th\ J-S}$	300	K/W
ESD (Classification acc. AEC Q101)	ESD_{HBM}	2000	V
	ESD_{MM}	200	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I _v	112	-----	224	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}	-----	120	-----	deg	I _F =20mA
Peak Wavelength	λ _p	-----	639	-----	nm	I _F =20mA
Dominant Wavelength	λ _d	627	----	639	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ	-----	20	-----	nm	I _F =20mA
Forward Voltage	V _F	1.75	----	2.35	V	I _F =20mA
Reverse Current	I _R	-----	-----	50	μA	V _R =5V

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.1V

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
R1	112	140	mcd	I _F =20mA
R2	140	180		
S1	180	224		

Note:
 Tolerance of Luminous Intensity: ±11%

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
1	627	630	nm	I _F =20mA
2	630	633		
3	633	636		
4	636	639		

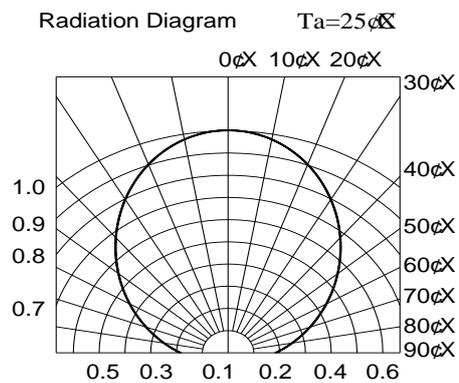
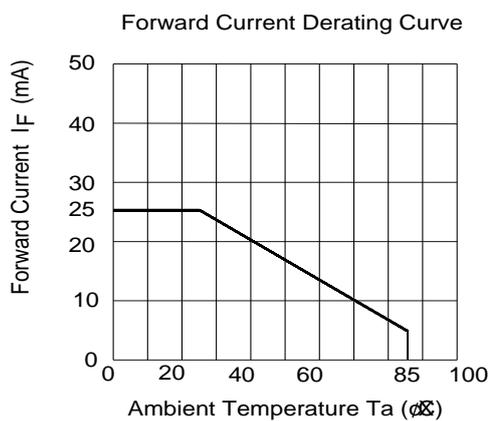
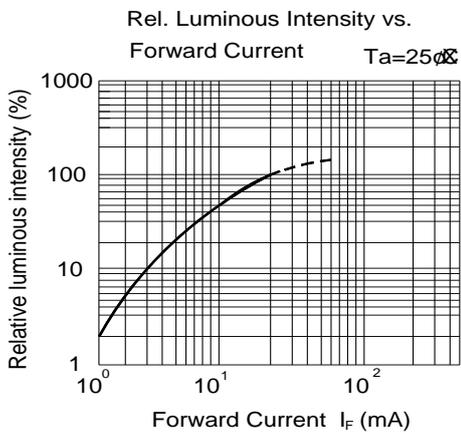
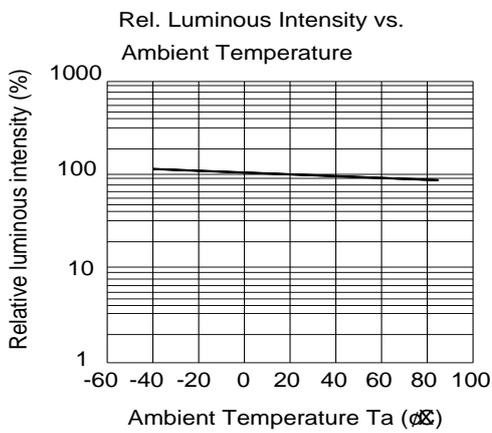
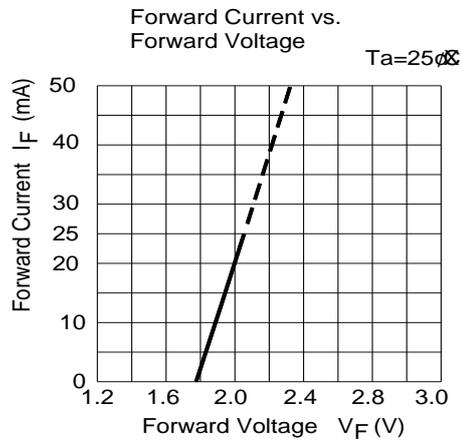
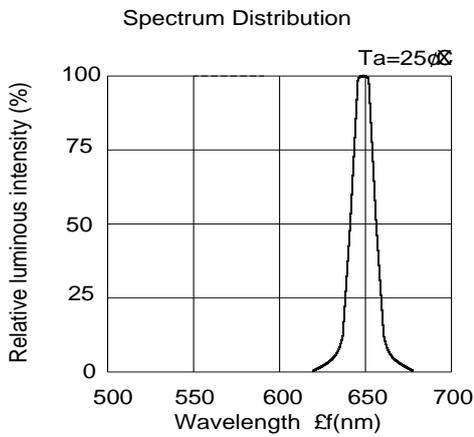
Note:
 Tolerance of Dominant Wavelength: ±1nm

Bin Range of Forward Voltage

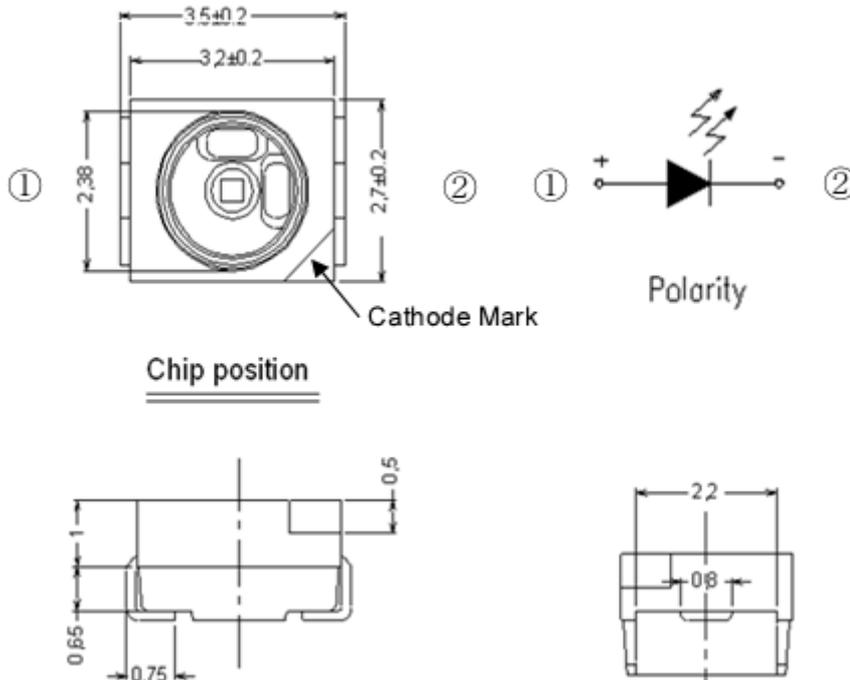
Bin Code	Min.	Max.	Unit	Condition
0	1.75	1.95	V	I _F =20mA
1	1.95	2.15		
2	2.15	2.35		

Note:
 Tolerance of Forward Voltage: ±0.1V

Typical Electro-Optical Characteristics Curves



Package Dimension



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

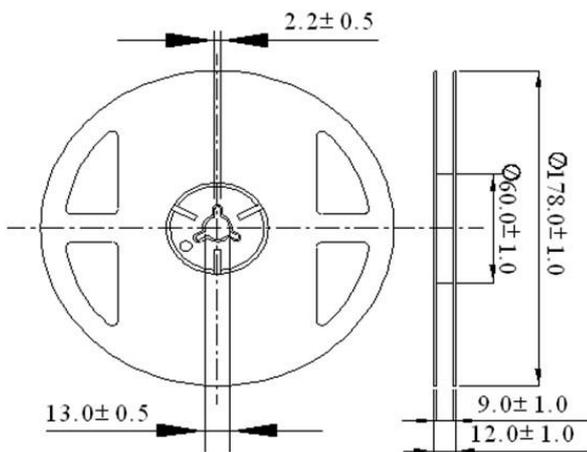
Moisture Resistant Packing Materials

Label Explanation

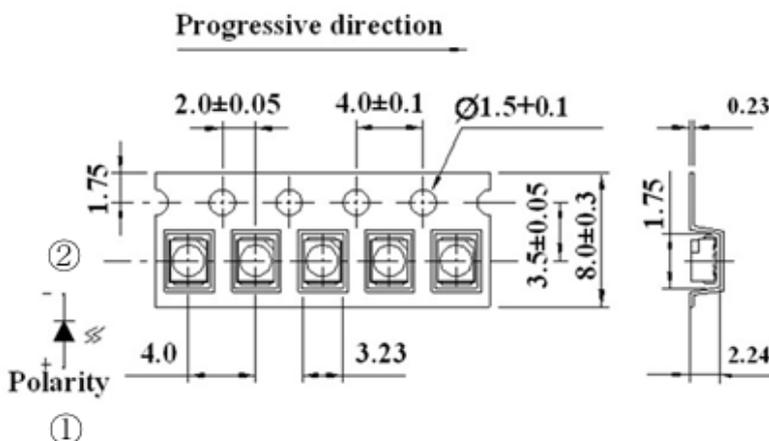


- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions

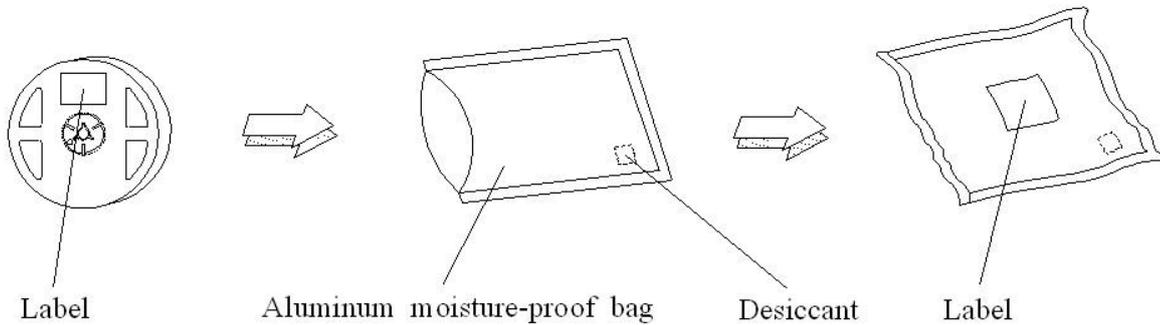


Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

Moisture Resistant Packing Process

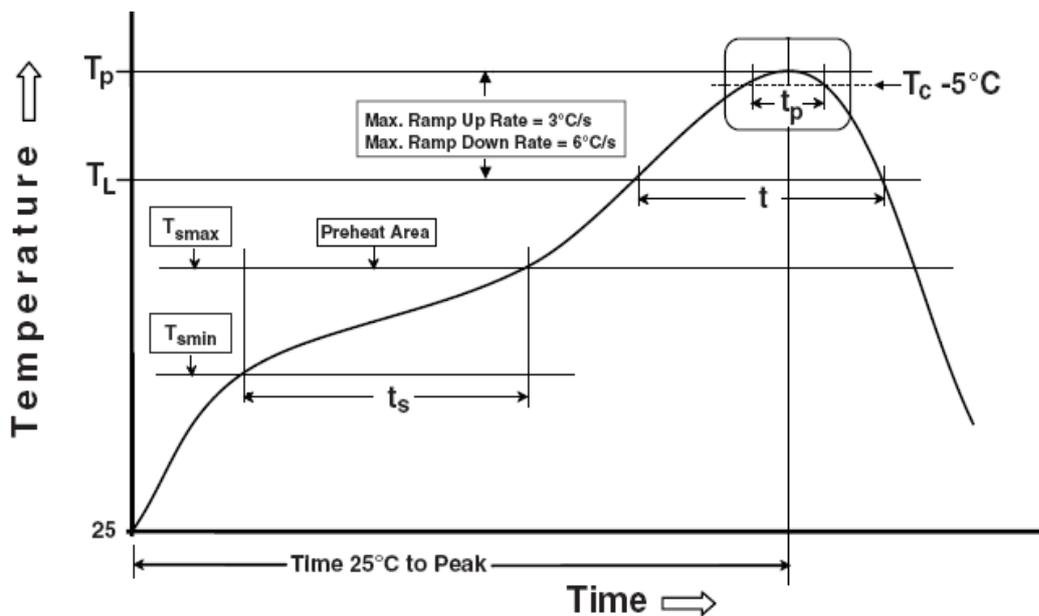


Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Preheat

Temperature min (T_{smin})

Temperature max (T_{smax})

Time (T_{smin} to T_{smax}) (t_s)

Average ramp-up rate (T_{smax} to T_p)

Other

Liquidus Temperature (T_L)

Time above Liquidus Temperature (t_L)

Peak Temperature (T_p)

Time within 5°C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$

Reference: IPC/JEDEC J-STD-020D

150 °C

200°C

60-120 seconds

$3^\circ\text{C/second max}$

217 °C

60-150 sec

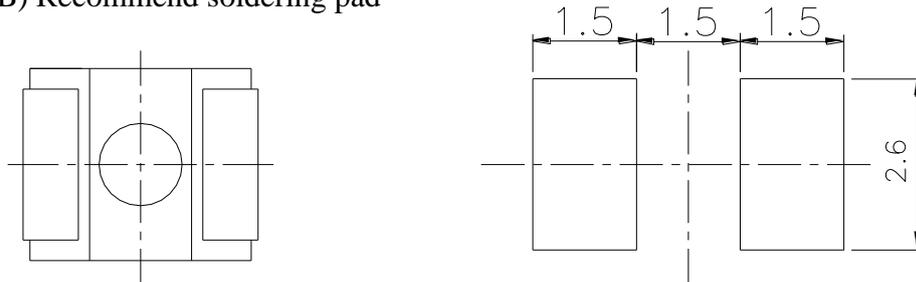
260°C

30 s

Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

All parameters are maximum body case temperature values and cannot be considered as a soldering profile. The body temperature was measured by soldering a thermal couple to the soldering point of LEDs.

(B) Recommend soldering pad



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

3. Storage

- 3.1 Moisture proof bag should only be opened immediately prior to usage.
- 3.2 Environment should be less than 30°C and 90% RH when moisture proof bag is opened.
- 3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.
- 3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 25 hours.

4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350°C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

5. Usage

Do not exceed the values given in this specification.

Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

Revision History

Rev.	Modified date	File modified contents
1	2014/4/30	New Spec